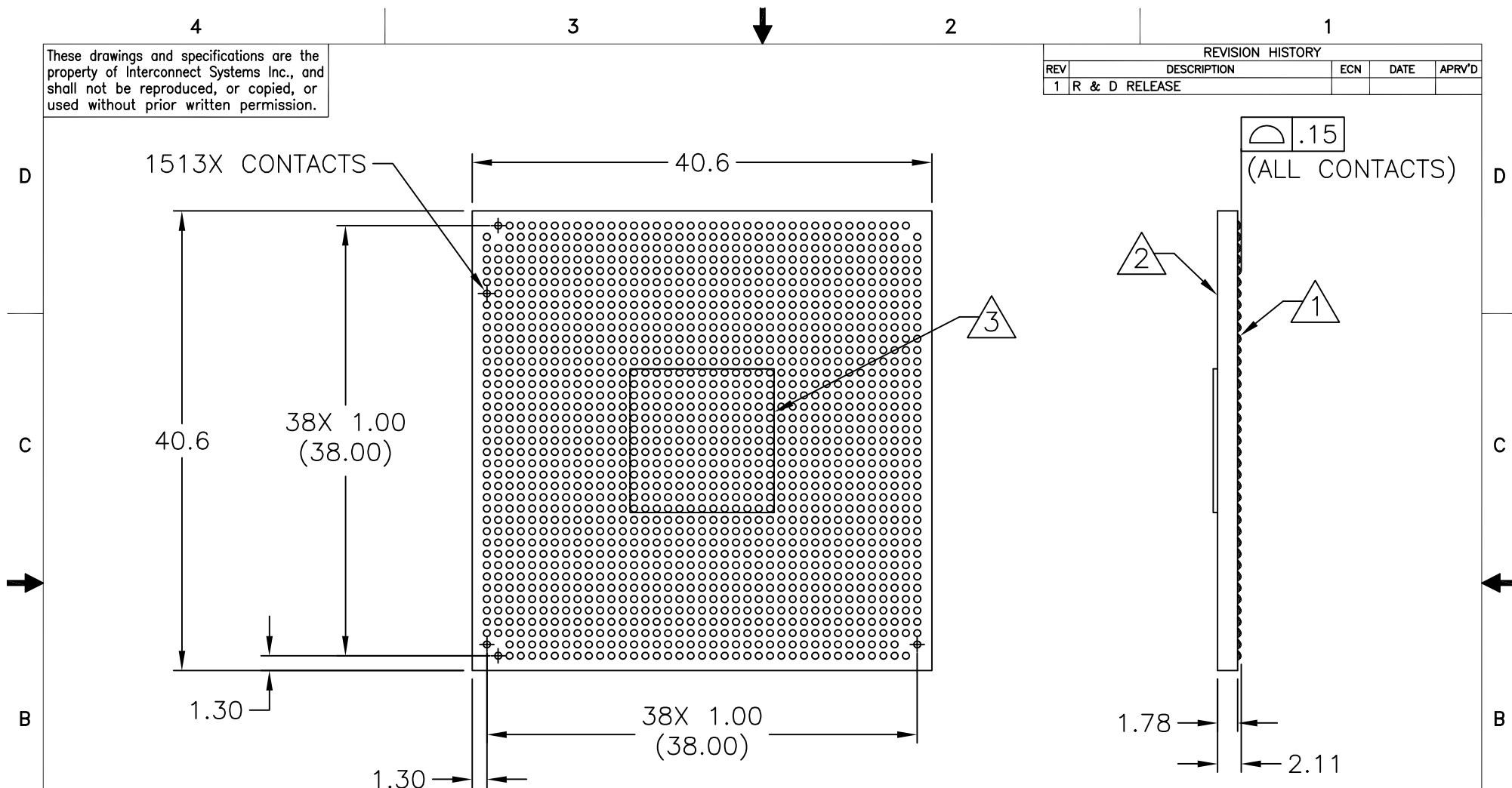


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REVISION HISTORY				
REV	DESCRIPTION	ECN	DATE	APRV'D
1	R & D RELEASE			



NOTES:

- 1. CONTACT MATERIAL: BERYLLIUM COPPER.
CONTACT PLATING: GOLD OVER NICKEL.
- 2. INSULATOR MATERIAL: FR4, BLACK, Tg125°C.
- 3. KAPTON TAPE FOR PICK AND PLACE.
- 4. RECOMMENDED KEEP OUT ZONE: NO COMPONENTS WITHIN 2.16 [.085] OF INSULATOR BODY FOR EXTRACTION TOOL CLEARANCE.

METRIC CUSTOMER APPLICATION DRAWING

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS [ALTERNATE] DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: ± 10° FRACTIONS: ± 1/64 DECIMALS: .X ±.25 .XX ±.13 .XXX ±.013	CONTRACT NO.	 INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012	
	DRAWN BY H. RANGLES		DATE 10/28/04
	DESIGNER H. RANGLES		DATE 10/28/04
	CHECKER		DATE
QA	DATE	TITLE HiLo SOCKET, 39 X 39, 1513 CONTACTS, 1.0mm PITCH, FOR ISI P/N: HLS-391513-B-10	
PROCESS ENG.	DATE	SIZE A	
SCALE 2/1		DRAWING NO.	
SHEET 1 OF 1		REV 1	